

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20190508000 Datasheet for MCP6291, MCP6292, MCP6294 Information Only

Date: May 09, 2019 **To:** Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team (PCN www admin team@list.ti.com).

Sincerely,

PCN Team SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICEMCP6292IDGKT
MCP6294IDR
MCP6294IPWT

CUSTOMER PART NUMBER

null null null

Technical details of this Product Change follow on the next page(s).

PCN	Number:	20190508	ດດດ	p	CN Date:	Ма	av.	9, 20	19	
Title				6292, MCP6			<u> </u>	<i>3,</i> 20		
	omer Contact:	PCN Manac		0_0		D)eı	ot:	Quality Services	
Change Type:										
Assembly Site Design Wafer Bump Site									er Bump Site	
				Data Sheet				Wafer Bump Material		
Assembly Materials			Part number change			_	Wafer Bump Process			
Mechanical Specification			H	Test Site			_		er Fab Site	
Packing/Shipping/Labeling			Test Process	est Process			Wafer Fab Materials Wafer Fab Process			
Notification Details										
Description of Change:										
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.										
	Texas Instruments						ı	MCP62	91, MCP6292, MCP6294	
						SBO	S87	9C –JUL	Y 2017-REVISED JANUARY 2019	
Changes from Revision B (April 2018) to Revision C Page										
	Deleted SOT-23 package preview notation in <i>Device Information</i> table									
	Added SC70 package to Device Information table									
	Added DCK package information to Device Comparison Table									
	Deleted DBV package preview notation from Pin Configuration and Functions section									
	Added DRV (SOT 23) and DCK (SC70) thermal information Added DRV (SOT 23) and DCK (SC70) thermal information									
_	Added DBV (SOT-23) and DCK (SC70) thermal information									
Changes from Revision A (October 2017) to Revision B										
•	Added DGK package to Thermal Information table									
The datasheet number will be changing Device Family				Change From:			Chan	ge To:		
,				SBOS879A			SBOS879C			
L	P6291, MCP6292					SBUS	8/90			
These changes may be reviewed at the datasheet links provided.										
http://www.ti.com/product/MCP6294										
Reason for Change:										
To reflect the device pin descriptions accurately.										
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):										
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.										
Changes to product identification resulting from this PCN:										
None.										
Prod	luct Affected:									
	MCP6291IDBVR	МСР	629	291IDCKR MCP6292		2ID0	GK	R	MCP6292IDGKT	
	MCP6292IDR	MC	P62	94IDR	MCP629	4IPWR			MCP6294IPWT	

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN www admin_team@list.ti.com